

#### Express recovery diode Reverse Voltage50V-600v Forward current-1A

#### **Features**

Glass passivated chip
High surge current capability
Ldeal for surface mounted applications
Low power loss, high efficiency
Plastic Case Material has UL Flammability

#### Mechanical Data

Package: SMAF

Terminals:Tin Plated leads, solderable per

Mil-STD-750 Method 2026

Polarity: As marked

Molding compound meets UL 94 V-0 flammability rating,

**ROHS-compliant** 





#### Maximum Ratings (Ta=25℃ Unless otherwise specified)

Tuna Numbar	CYMBOL	ES2					
Type Number	SYMBOL	AF	BF	DF	GF	JF	Umit
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	V
Maximum RMS Voltage	V <sub>RMS</sub>	35	70	140	280	420	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	200	400	600	V
Maximum Average Forward Rectified Current	IO <sub>(AV)</sub>	2.0				Α	
Peak Forward Surge Current 8.3ms Single half-sine-wave superimposed on rated load(JEDEC Method) on rated	IFSM _	50.0 100.0				Α	
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25 ℃	II OW					Α	
Current squared time @1ms≤t8.3≤ms Tj=25℃,Rating of per diode	l <sup>2</sup> t	10.4				$A^2S$	
Maximum Forward Voltage at 2.0A DC	$V_{FM}$		0.95 1.3 1.7			1.7	V
Maximum Reverse Current TA = $25  ^{\circ}$	IR -	5.0			uA		
at Rated DC Blocking Voltage $TA = 125^{\circ}$ C	IIX	100.0		uA			
Maximum reverse recovery time	Trr	35.0				ns	
Typical Thermal Resistance Between junction and	$R_{QJa}$	65.0				°C/W	
Operating Junction Temperature Range	T <sub>J</sub>	—55to+150			$^{\circ}$		
Storage Temperature Range	T <sub>STG</sub>	—55to+150				$^{\circ}$ C	

FIG. 1MAXIMUM AVERAGE FORWARD CURRENT DERATING

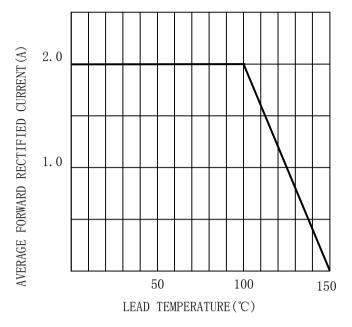


FIG. 2TYPICAL FORWARD CHARACTERISTICS

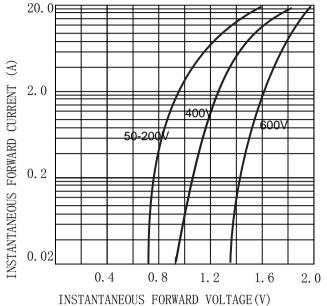


FIG. 3MAXIMUM NON-REPEITIVE SURGE CURRENT

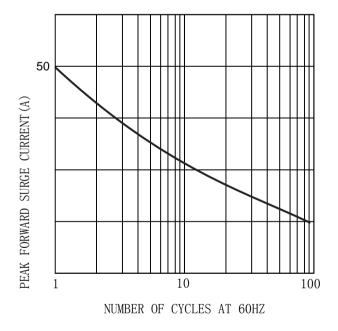
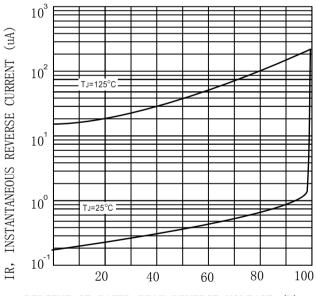


FIG. 4 TYPICAL REVERSE CHARACTERISTICS (per element)



PERCENT OF RATED PEAK REVERSE VOLTAGE (%)

#### **MARKING INFORMATION**



= Logo

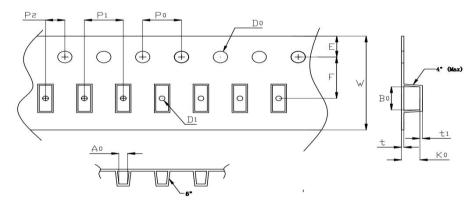
\*\*\*\* = Date Code Marking

ES2\* = Marking Code

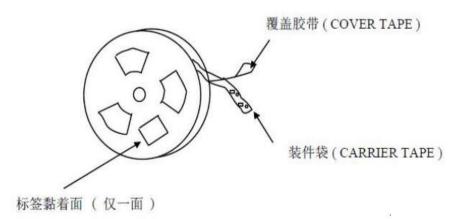
Print according to customer request

### **PACKING REQUIRMENTS**

Carrier tape packing



Specificati ons	Carrier tape type	Ao	Во	Ко	Ро	W	t	Exiplain
SMAF	Anti-static	2.83± 0.10	4.9± 0.10	1.45± 0.05	4.00± 0.10	12.0± 0.10	0.23± 0.05	

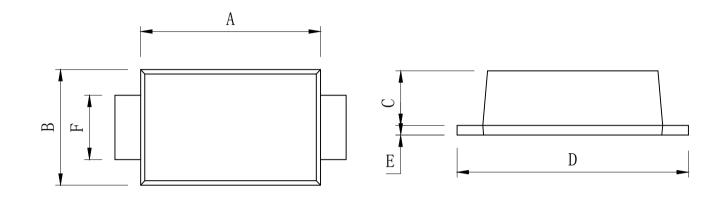


DEVICE Tape TYPE width		13"Reel		7"Reel			
	width	Q'TY/REEL (pcs)	BOX/CAR TOON	Q'TY/REEL (pcs)	Q'TY/REEL (pcs)	BOX/CAR TOON	Q'TY/REEL (pcs)
SMAF	12mm	10000	20	200000	3000	64	192000



### Outline Dimensions

### **SMAF**



SMAF							
DIM	INC	HES	MM				
	MIN	MAX	MIN	MAX			
A	0. 13	0. 15	3. 2	3.8			
В	0.09	0. 11	2.3	2. 7			
С	0.03	0.05	0.8	1.2			
D	0. 16	0.20	4	5			
Е	/	0.01	/	0.3			
F	0.04	0.08	1	2			



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